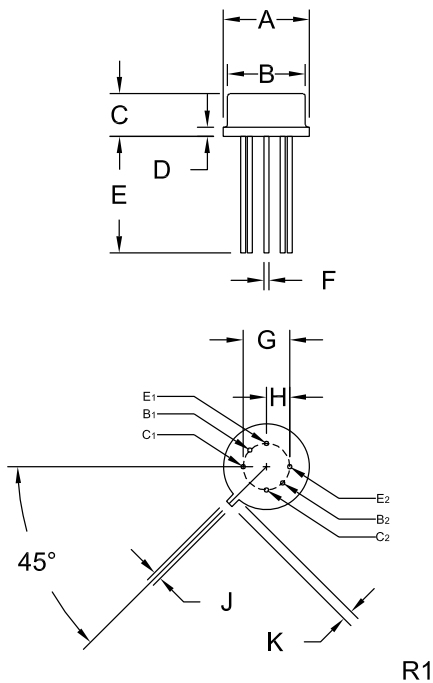


# Package Details - TO-78

## Mechanical Drawing



DIMENSIONS				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A (DIA)	0.335	0.370	8.51	9.40
B (DIA)	0.305	0.335	7.75	8.51
C	0.150	0.185	3.81	4.70
D	-	0.040	-	1.02
E	0.500	-	12.70	-
F (DIA)	0.016	0.021	0.41	0.53
G	0.200		5.08	
H	0.100		2.54	
J	0.028	0.034	0.71	0.86
K	0.029	0.045	0.74	1.14

TO-78 (REV: R1)

**Lead Code:**  
As indicated on mechanical drawing.

### Packing options:

#### Bulk - Packing Code: D

D = White corrugated box with black conductive coating  
(surface resistivity of  $<10^5$  ohms per square).

**Bulk Packing Quantity: 100**

# Material Composition Specification

## TO-78 Case



Device average mass ..... 1.1 g  
 Fluctuation margin ..... +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	9.09%	100	doped Si	7440-21-3	9.09%	100	90,909
bond wire	alloy	.0001%	.001	Al	7429-90-5	.0001%	.001	1
header	steel	54.55%	600	Fe	7439-89-6	31.91%	351	319,090
				glass	Proprietary	22.53%	248	225,272
				Au	7440-57-5	.055%	0.6	545
				Ni	7440-02-0	.055%	0.6	545
can	alloy	36.37%	400	Fe	7439-89-6	36.33%	399.6	363,272
				Ni	7440-02-0	.036%	0.4	364
plating*	tin/lead process	.00009%	.001	Sn	7440-31-5	.00007%	.0008	1
				Pb	7439-92-1	.00002%	.0002	0
	100% tin process	.00009%	.001	Sn	7440-31-5	.00009%	.001	1

\*For Lead Free plating, add suffix "LEAD FREE" to part number.  
 For Tin/Lead plating, add suffix "TIN/LEAD" to part number.  
 No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

### Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (3-June 2011)